

# MECHANICAL CASE OUTLINE

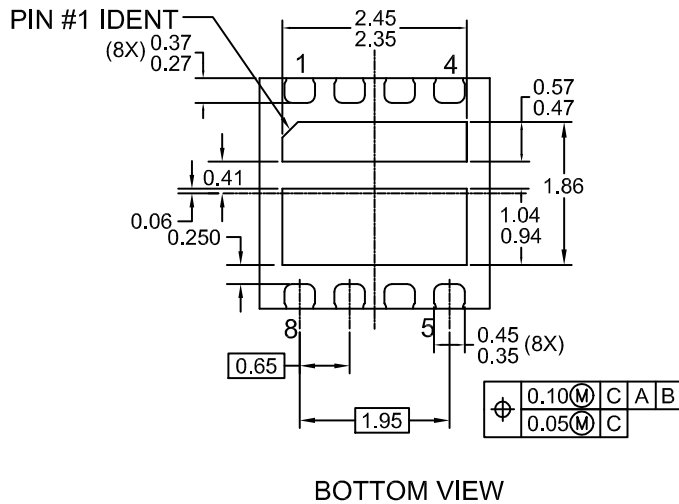
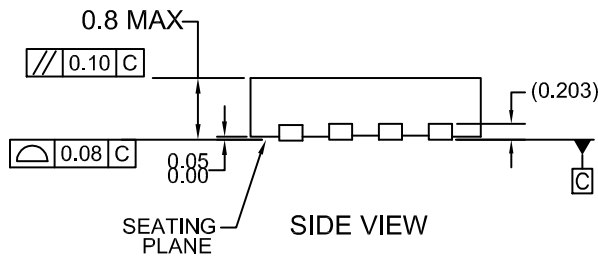
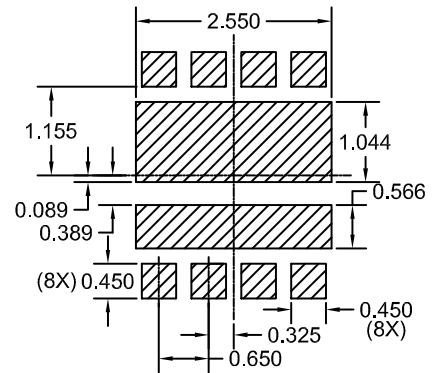
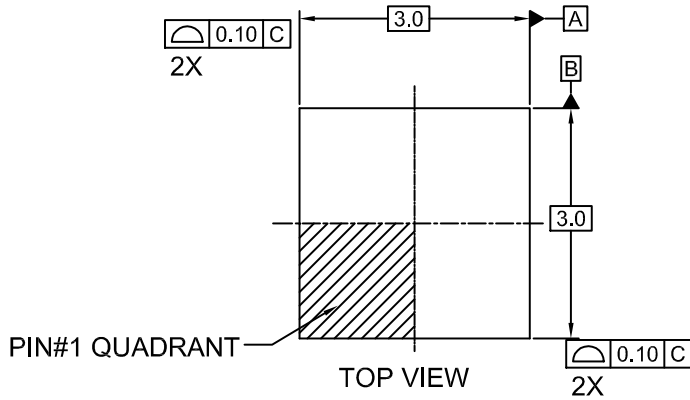
## PACKAGE DIMENSIONS

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WDFN8 3x3, 0.65P  
CASE 511DE  
ISSUE O

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### NOTES:

- A. DOES NOT CONFORM TO JEDEC REGISTRATION MO-229
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

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